

What is claimed is:

1. An optical module comprising:

an interconnect board which includes a base board and an interconnecting pattern  
5 formed on the base board;

an optical chip which includes an optical section and an electrode which  
electrically connects the optical section and the interconnecting pattern; and  
a body material which holds a lens which concentrates light on the optical section,  
wherein the body material is directly attached to the optical chip.

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2. The optical module as defined in claim 1,

wherein an opening is formed in the base board,

wherein the optical chip is bonded face down to the interconnect board so that the  
optical section faces the opening, and

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wherein the body material is attached to the optical chip through the opening.

3. The optical module as defined in claim 1, wherein the body material is attached  
to a surface of the optical chip on which the optical section is formed.

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4. The optical module as defined in claim 1, further comprising a resin section  
which is provided between the body material and the interconnect board to bond the body  
material to the interconnect board.

5. The optical module as defined in claim 4,

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wherein the optical chip is bonded face up to the interconnect board,

wherein the electrode and the interconnecting pattern are electrically connected  
through a wire, and

wherein the resin section seals at least the wire.

6. The optical module as defined in claim 5,

5 wherein a space having a shape which surrounds the wire, and a hole which has a width smaller than a width of the space and opens to an outside from the space are formed in the body material, and

wherein the space is filled with the resin section.

7. The optical module as defined in claim 1, wherein the body material is attached

10 to the optical chip in a region except the optical section.

8. The optical module as defined in claim 1,

wherein the optical chip further includes a cover provided to cover the optical section, and

15 wherein the body material is attached to the cover.

9. The optical module as defined in claim 1,

wherein the cover includes a plate section disposed above the optical section, and a spacer section which supports the plate section,

20 wherein the spacer section is attached to the optical chip, and

wherein the body material is attached to the plate section.

10. The optical module as defined in claim 1, wherein the body material is bonded

to the optical chip through an adhesive sheet material.

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11. The optical module as defined in claim 1, wherein the body material is bonded

to the optical chip through an adhesive.

12. An electronic instrument comprising the optical module as defined in claim 1.

13. A method of manufacturing an optical module comprising:

5        mounting an optical chip which includes an optical section and an electrode on an interconnect board which includes a base board and an interconnecting pattern formed on the base board so that the electrode is electrically connected with the interconnecting pattern; and

10        directly attaching a body material which holds a lens which concentrates light on the optical section to the optical chip.